



# Leveraging Government, University and VC Funding to Bring a NanoTechnology to Market

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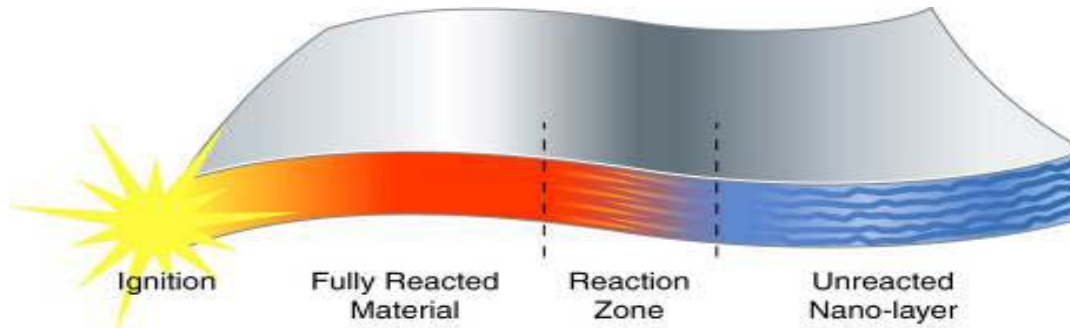
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- Introduce NanoFoil and NanoBond
- RNT Products, and Applications
- Company Profile
- History: Technology, Company, Funding

# NanoFoil®: The First and Only Nano-Engineered, Localized Energy Source



**RNT manufactures NanoFoil® a platform technology that delivers energy in a controlled and precise manner.**



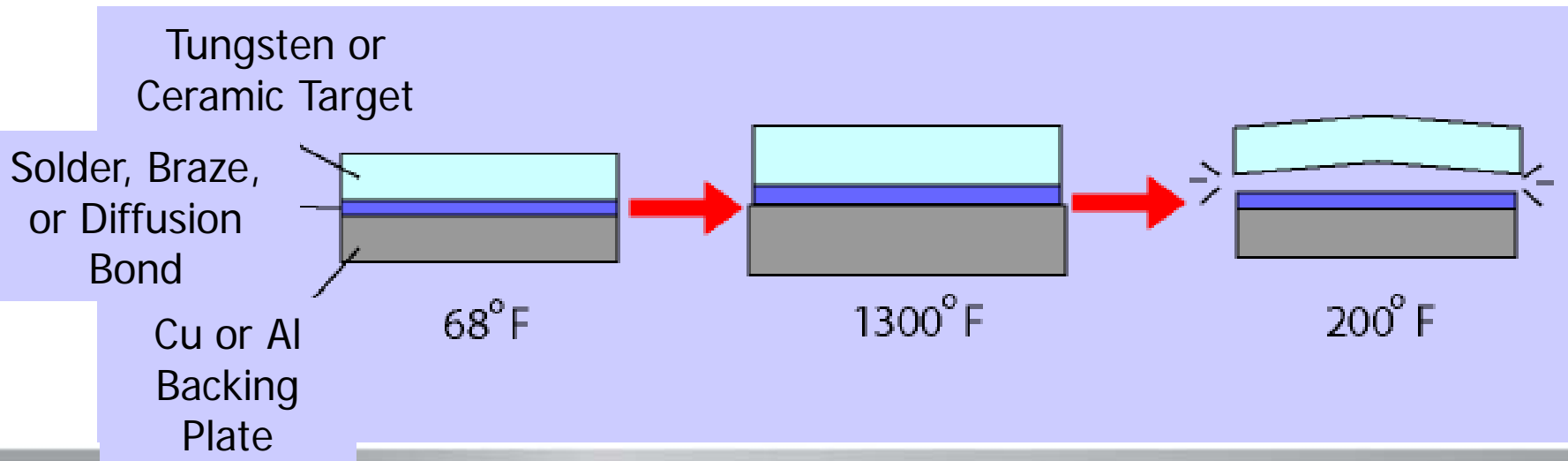
## **Revenue Model:**

- RNT manufactures and sells NanoFoil®  
Sell direct and through distributors**
- RNT Sublicenses the right to use the foil  
(NanoBond®)**

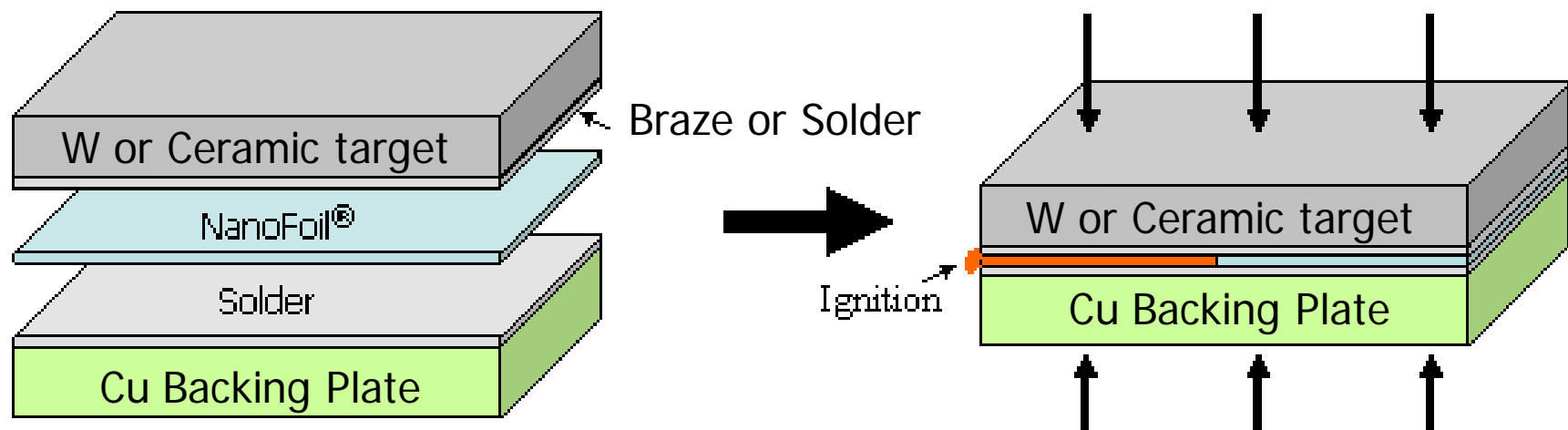


# The Coefficient of Thermal Expansion (CTE) Challenge

- Many Metal/Metal and Metal/Ceramic pairs shrink at different rates on cooling
- Large thermal stresses develop when soldering, brazing or diffusion bonding dissimilar materials
- Warping and debonding of materials can occur

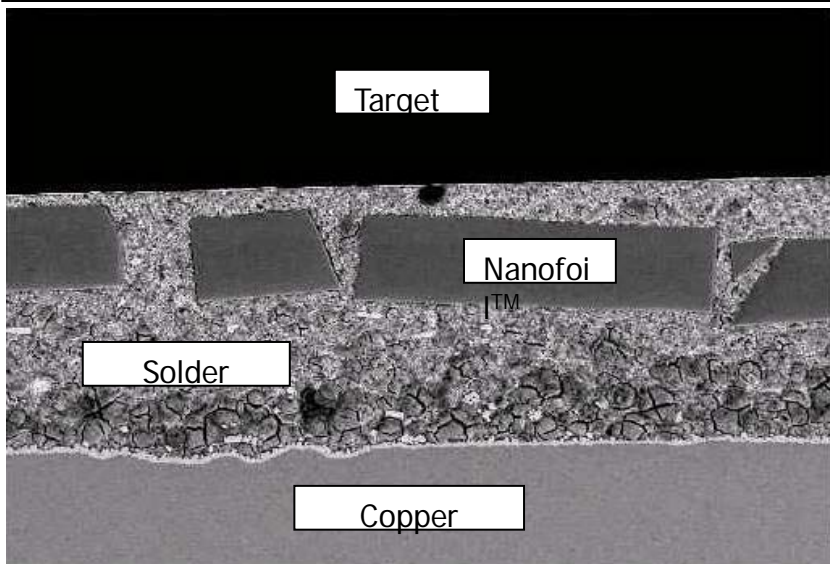
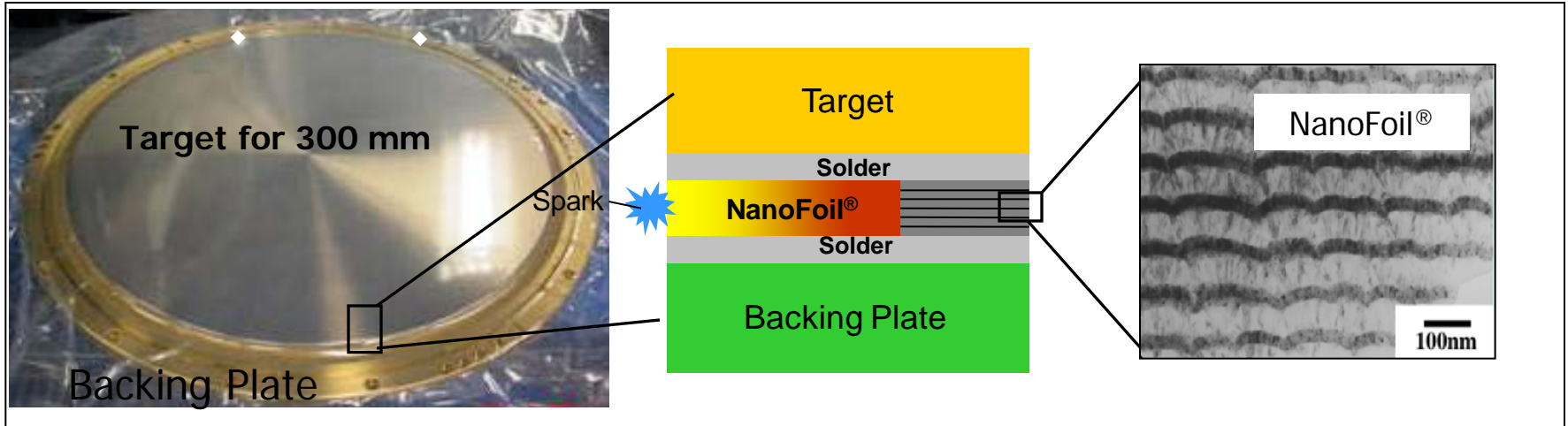


- Components are coated with solder or braze
- Insert NanoFoil<sup>®</sup> and apply pressure at room temperature
- Use heat from the NanoFoil<sup>®</sup> to melt solder or braze



*A Foil Replaces the Furnace or Hotplate*

# The NanoBond Solution



- No Thermal Damage of Materials
- Minimize Deflection or Cracking

- **Sputter Target Bonding**

- Metal to metal bonding
- Metal to ceramic bonding
- Currently serves planar target market, developing for rotatable target market



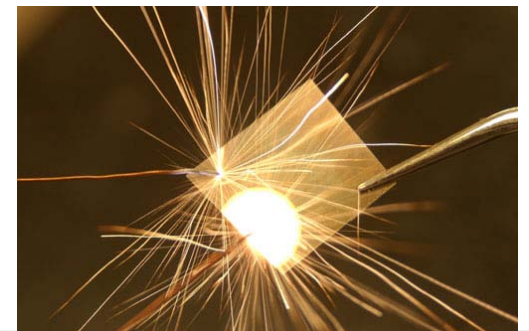
- **Electronic Assembly**

- Thermally sensitive applications
- Targeted applications
  - Manufacturer would prefer the strength of a soldered bond
  - Sole option in past has been to use adhesive technology

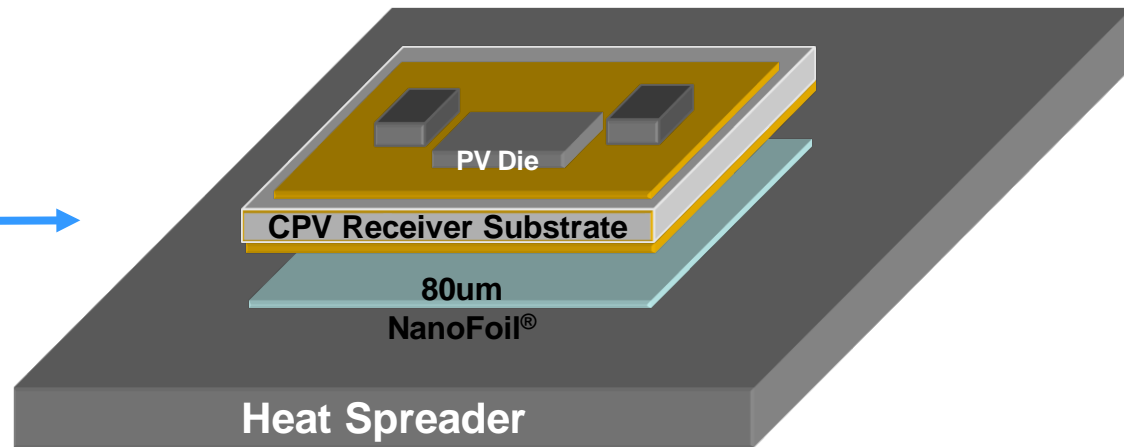
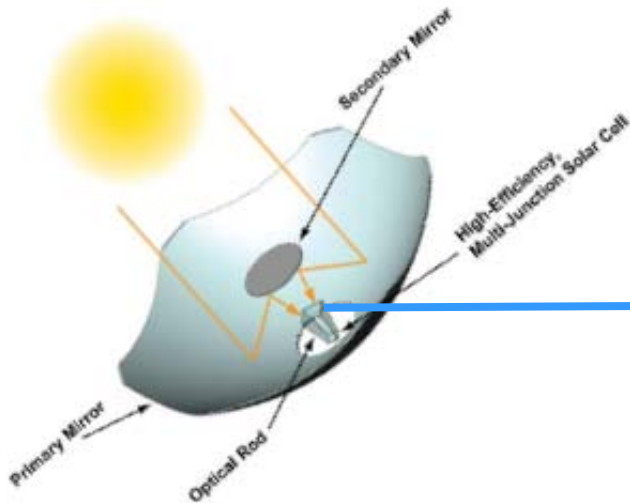


- **Energetics**

- Ignition of flares or propellants
- Green delays, detonators and fuses for explosives
- Heat source for thermal batteries



# Concentrated PV Application – Receiver Module Assembly



## NanoBond® Advantages - In The System

- CPV operation with higher efficiency and reliability
- CPV operation at higher sun magnification

## NanoBond® Advantages - In The Bond

- Thermal performance 6-10 times better than epoxy bonds
- True metallic bond without damaging exposure to solder reflow temperatures
- Low residual stress enabling superior metal-to-ceramic bonding



- Located in Hunt Valley, MD (just north of Baltimore)
  - Facility includes Production, Application Engineering, and R&D
- Experienced Management Team
  - RF Micro Devices, Heraeus, Denton Vacuum, Parker Hannifin, Johns Hopkins University
- Venture Financed (Credit Suisse, Siemens, Sevin Rosen, Toucan, SAS, DBED, etc)
- Producing and Selling NanoFoil® in multiple forms
- Acquisition by Indium Corporation of America
  - Sept 18, 2009
  - Excellent opportunity to leverage existing customer base and complementary products !!

- Lawrence Livermore National Lab (LLNL), mid 1990's
  - Initial development
  - Three patents filed
- Johns Hopkins University (JHU), 1995 - present
  - Significant additional development
  - Setup research group and collaborations (Professor Omar Knio, Professor Todd Hufnagel)
  - Multiple sources of research funding (NSF, ARL, 3M, TEDCO)
  - Five patents filed
- RNT has exclusive licenses from both entities

- JHU Press Release in 1996 – Prof Tim Weihs
  - Covers the potential of use of foils for joining
  - Generates over 300 leads
  - Demonstrates real commercial interest but have proof of concept
- Corporate Requests 1999-2000
  - Agilent Technologies (funds development at JHU)
  - Requests to purchase foil
  - Dr. Tim Weihs decides to start company with Dr. Omar Knio
- Company Incorporated in 2001
  - Enter Emerging Technology Center’s Incubator Program
    - John Fini (advisor)
    - Connected with people for legal, business, and financial advice
    - Learning as quickly as possible
  - Seek JHU and LLNL licenses

- Seed Money in 2001
  - Founders
  - TEDCO \$50K Grant to JHU
- Series A in mid 2002
  - Raised \$2M from Toucan Capital, SAS Investors, & MD-DBED
  - Won ~\$4m in Gov't Grants - 1 NIST-ATP, 3 SBIRs (2 NSF, 1 Army)
  - \$50K from TEDCO
- Series B in 2004
  - Raised \$8M from Sevin Rosen, Toucan, SASI, etc.
  - Hired experienced CEO to bring forward commercialization
- Series C in 2007
  - Raised \$17M from Siemens, Sevin Rosen, Credit Suisse
  - Additional \$5M from Credit Suisse

- The Insertions of New Materials often Takes 20 Years from Concept to Full Adoption (15 years so far)
  - Need to develop material and applications (multiple)
  - Customers are usually slow to put new materials into their production lines
  - Initial applications often do not work (air bag, heat sinks for CPUs and GPUs, propellant ignition)
  - Typical timeline is too long for VC-only funding
- Government Funding Supports Initial Development
  - NSF Grant #1 – lead to LED application
  - NSF Grant #2 – lead to sputter target application
  - Helped attract VC funding (B Round)
- Excellent opportunity.... But must be focused
  - Keep eye on commercialization... avoid becoming an SBIR-only company

- **Early government support was an absolutely critical part of making RNT a reality !!**
- **Early government support made early technical success made possible.**
- **The combination of government support and technical success made VC funding possible.**
- **VC funding provided the large dollars (\$32M) needed to pursue commercialization.**
- **Early commercialization made a strategic acquisition possible.**
- **Note Of Caution !! Materials developments require patience and perseverance**
  - **Long insertion time for new materials**
  - **A materials start-up is a marathon not a sprint !!**

